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Patent No. 09/830,490

Response Under 37 CFR § 1.116

Expedited Procedure

Examining Group 1734

Amdt. dated April 17, 2003

Reply to Office Action of December 26, 2002

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A process for producing IC cards, comprising the steps of:
continuously feeding a mount substrate having unevenness of components on the surface
thereof and simultaneously feeding a pair of sheet members on both surface sides of the mount
substrate in such a manner that the mount substrate is interposed between the pair of sheet members;
feeding an adhesive in fluid condition on the surface of the sheet members; and
regulating a distance between the pair of sheet members into a constant spacing and
hardening the adhesive by interposing the mount substrate between the surfaces of the sheet
members on which the adhesive is fed.

2. (Currently Amended) ~~The A process as claimed in claim 1 for producing IC cards,~~
comprising the steps of:
continuously feeding a mount substrate and simultaneously feeding a pair of sheet members
on both surface sides of the mount substrate in such a manner that the mount substrate is interposed
between the pair of sheet members;
feeding an adhesive in fluid condition on the surface of the sheet members; and
regulating a distance between the pair of sheet members into a constant spacing and
hardening the adhesive by interposing the mount substrate between the surfaces of the sheet

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members on which the adhesive is fed, wherein one of the pair of sheet members consists of a release sheet.

3. (Currently Amended) ~~The A process as claimed in claim 1 for producing IC cards, comprising the steps of:~~

continuously feeding a mount substrate and simultaneously feeding a pair of sheet members on both surface sides of the mount substrate in such a manner that the mount substrate is interposed between the pair of sheet members, wherein at least one of the pair of sheet members consists of a release sheet, and which further comprises the steps of,

feeding an adhesive in fluid condition on the surface of the sheet members;

regulating a distance between the pair of sheet members into a constant spacing and hardening the adhesive by interposing the mount substrate between the surfaces of the sheet members on which the adhesive is fed;

stripping the release sheet from the mount substrate after the hardening of the adhesive; and

sticking a laminate sheet member onto adhesive layer surface exposed as a result of the stripping of the release sheet.

4. (Previously Added) The process of claim 1, wherein the distance between the sheet members is narrowed gradually.